

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Packaging of components for automatic handling –
Part 3: Packaging of surface mount components on continuous tapes**

**Emballage de composants pour opérations automatisées –
Partie 3: Emballage des composants pour montage en surface en bandes
continues**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –**Part 3: Packaging of surface mount components
on continuous tapes**

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International Standard IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This sixth edition cancels and replaces the fifth edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition of a table of the classification to symbols concerning tape, reel and common symbols;
- b) additions of a figure of example of polarity and orientation and a figure of example of dot seal;
- c) revision of requirements for camber;

d) addition of a definition of design value with regard to tilt.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
40/2643/FDIS	40/2649/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60286 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components and singulated dies for test purposes and other operations.

Withdrawn